

ABSTRACT OF THE DISCLOSURE

5 A cooling system for cooling a circuit board including first and second heat sources. The cooling system includes a cooling apparatus configured to absorb heat dissipated from the heat sources, and features an actuator configured to retractably actuate the cooling apparatus into conforming thermal contact with the heat sources. The cooling apparatus may be compliant, and it may be compliantly mounted to one or more supports.

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A modular semiconductor chip cooling system having a readily openable enclosure defining a chamber configured to hold a printed circuit board carrying components to be cooled. The enclosure can include a reservoir, a condenser and a pump. Sprayers within the chamber are adjustably mounted on one or more brackets to allow each sprayer to be set for the individual height of its respective component. The enclosure can be readily removed from a computer system through a quick release connection. The computer system can include a condenser and pump to operate all its modular cooling systems, removing the condensing function from the individual modules.